

## PMP8851 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		PMP8851 PCB Rev B	Any	Printed Circuit Board	
C1, C10, C11	3	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	0402
C2, C3	2	1uF	GRM21BR71H105KA12L	MuRata	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0805	0805
C4, C5	2	22uF	C2012X5R0J226M	TDK	CAP, CERM, 22uF, 6.3V, +/-20%, X5R, 0805	0805
C7	1	330pF	C1005C0G1H331J	TDK	CAP, CERM, 330pF, 50V, +/-5%, C0G/NPO, 0402	0402
C8	1	0.01uF	C1005X7R1C103K	TDK	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0402	0402
C9	1	10uF	C1608X5R0J106M	TDK	CAP, CERM, 10uF, 6.3V, +/-20%, X5R, 0603	0603
C101	1	47pF	GRM1555C1E470JA01D	MuRata	CAP, CERM, 47pF, 25V, +/-5%, C0G/NPO, 0402	0402
D1	1	0.7V	B360A-13-F	Diodes Inc.	Diode, Schottky, 60V, 3A, SMA	SMA
D2	1	39V	MM5Z39VT1	ON Semiconductor	Diode, Zener, 22V, 300mW, SOD-523	SOD-523
D3	1	SK24-TP	SK24-TP	Micro Commercial Co	Diode, Schottky, 20V, 2A, SMB	SMB
D4	1	Green	LTST-C190GKT	Lite-On	LED, Green, SMD	1.6x0.8x0.8mm
D100	1	15V	MM5Z15VT1	ON Semiconductor	Diode, Zener, 22V, 300mW, SOD-523	SOD-523
F1	1		F0603E3R00FSTR	AVX	Fuse, 3 A, 32 V, SMD	0603
J1	1	C-292303-x			Connector, USB TH	
L1	1	22uH	XAL5050-223MEB	Coilcraft	Inductor, Shielded, Composite, 22uH, 3.4A, 0.1 ohm, SMD	XAL5050
L100	1	30 ohm	MPZ2012S300AT000	TDK	Ferrite Bead, 30 ohm @ 100 MHz, 6 A, 0805	0805
Q1	1	40 V	MMDT3946-7-F	Diodes Inc.	Transistor, NPN/PNP Pair, 40 V, 0.2 A, SOT-363	SOT-363
Q2	1	60V	FDC5614P	Fairchild Semiconductor	MOSFET, P-CH, 60V, -3A, SOT-23-6	SOT-23-6
R1	1	11k	CRCW040211K0JNED	Vishay-Dale	RES, 11k ohm, 5%, 0.063W, 0402	0402
R2	1	200k	CRCW0402200KFKED	Vishay-Dale	RES, 200k ohm, 1%, 0.063W, 0402	0402
R3	1	499k	CRCW0402499KFKED	Vishay-Dale	RES, 499k ohm, 1%, 0.063W, 0402	0402
R4	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0k ohm, 1%, 0.063W, 0402	0402
R5	1	3.01k	CRCW04023K01FKED	Vishay-Dale	RES, 3.01k ohm, 1%, 0.063W, 0402	0402
R6, R14	2	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100k ohm, 1%, 0.063W, 0402	0402
R7	1	82.5k	CRCW040282K5FKED	Vishay-Dale	RES, 82.5k ohm, 1%, 0.063W, 0402	0402
R8	1	47.5k	CRCW040247K5FKED	Vishay-Dale	RES, 47.5k ohm, 1%, 0.063W, 0402	0402
R9	1	2.00k	CRCW04022K00FKED	Vishay-Dale	RES, 2.00k ohm, 1%, 0.063W, 0402	0402
R10, R12	2	1.00k	CRCW04021K00FKED	Vishay-Dale	RES, 1.00k ohm, 1%, 0.063W, 0402	0402
R13	1	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
R15	1	22.1k	CRCW040222K1FKED	Vishay-Dale	RES, 22.1k ohm, 1%, 0.063W, 0402	0402
R16	1	34.0k	CRCW040234K0FKED	Vishay-Dale	RES, 34.0k ohm, 1%, 0.063W, 0402	0402
R200	1	1.00Meg	CRCW04021M00FKED	Vishay-Dale	RES, 1.00Meg ohm, 1%, 0.063W, 0402	0402
TP1	1	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000
TP2	1	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
U1	1		TPS54340DDAR	Used in BOM report	IC REG BUCK ADJ 3.5A 8SO	eg: 0603, used in PnP report
U2	1		TPS2511DGN	Texas Instruments	USMB Dedicated Charging Port Controller and Current Limiting Power Switch, DGN0008E	DGN0008E
U3	1		TPD2E001IDRLRQ1	Texas Instruments	Automotive Catalog Low-Capacitance + / - 15 kV ESD-Protection Array for High-Speed Data Inter, 2 Channels, -40 to +85 degC, 5-pin SOT (DRL), Green (RoHS & no Sb/Br)	DRL0005A

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